IN THE CLAIMS:

Claim 1 (presently amended). A bonding apparatus comprised of a processing member that processing bonding parts, a first imaging device of high magnification that images a specific pattern, and a first offset calculating means that calculates an amount of offset between said processing member and said first imaging device based upon image data acquired by said first imaging device, said bonding apparatus further comprising:

a second imaging device that images said specific pattern, said second imaging device having low magnification that is lower than said first imaging device, and

a second offset calculating means that calculates an amount of deviation between a reference point of a first image data acquired by said first imaging device and a reference point of a second image data acquired by said second imaging device based upon said first image data and said second image data and wherein said second offset calculating means calculates said offset by:

performing reduction processing so that the image data with higher magnification obtained by said first imaging device and image data obtained by said second imaging device are caused to match an imaging magnification on a lower magnification side, and

comparing an image obtained by said reduction processing with said image data on said lower magnification side.

Claim 2 (original). The bonding apparatus according to Claim 1, wherein said second offset calculating means calculates said amount of deviation between said reference point of said first image data and said reference point of said second image data based upon:

a first magnification which is an imaging magnification of said first imaging device, and

a second magnification which is an imaging magnification of said second imaging device.

Claim 3 (canceled).

Claim 4 (presently amended). A bonding method used in a bonding apparatus which is comprised of a processing member that processes bonding parts, a high magnification first imaging device that images a specific pattern, a low magnification second imaging device that

images said specific pattern, and a first offset calculating means that calculates an amount of offset between said processing member and said first imaging device based upon image data acquired by said first imaging device, wherein:

said method calculates an amount of deviation between a reference point on a first image data acquired by said first imaging device and a reference point of a second image data acquired by said second imaging device, said calculating being performed based upon said first image data and said second image data, said calculating an amount of deviation by the steps of:

performing a reduction processing so that image data with a higher magnification obtained by said first imaging device and image data obtained by said second imaging device are caused to match an imaging magnification on a lower magnification side, and

comparing data subjected to said reduction processing with said image data on said lower magnification side.

Claim 5 (original). The bonding method according to Claim 4, wherein said amount of deviation between said reference point of said first image data and said reference point of said second image data is calculated based upon a first magnification which is an imaging magnification of said first imaging device and a second magnification which is an imaging magnification of said second imaging device.

Claim 6 (canceled).